

ABSTRACT OF THE DISCLOSURE

A method for making a semiconductor package includes preparing a die with bonding pads, forming conductive bodies on the die such that each conductive
5 body is electrically connected to a respective bonding pad and has a trace part offset from the respective bonding pad, forming an encapsulant on each bonding pad, forming a protective layer on the die and the encapsulant, and forming conductive bumps
10 such that each bump is electrically connected to the trace part of a respective conductive body and protrudes outwardly from the protective layer.